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(72)Inventor: **MORI RYUICHIRO****(54)SEMICONDUCTOR DEVICE****(57)Abstract:**

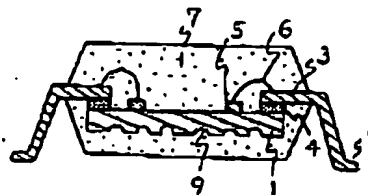
PURPOSE: To prevent a crack of a resin during a mounting operation by a method wherein a hollow is formed in a face where an inner lead part of a semiconductor element is not attached.

CONSTITUTION: A hollow 9 is formed on the rear of a semiconductor element 1; this hollow 9 is filled with a sealing resin 7. Thereby, a close contact force at an inner face between the semiconductor element 1 and the sealing resin 7 can be increased. As a result, even when a temperature is raised during a mounting operation, an exfoliation at an interface between the rear of the semiconductor element 1 and the sealing resin 7 is suppressed; it is possible to prevent a crack of the resin 7. Since the hollow is formed in a face other than a bonding face of an inner lead part of the semiconductor element, the close contact force between the semiconductor element and

the sealing resin is increased; even when the temperature is raised during the mounting operation, the exfoliation is hardly caused; it is possible to prevent the crack of the resin.

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